Bole Metal oxide Lead Dioxide (PbO2) 1309-600 0.01 1.0 0.1 Composition Silicon (S) 7440-21-3 0.5 99.0 10.1 Scolder Wire Tin alloy Tin (Sn) 7440-21-5 0.03 10.0 0.56 Solder Wire Silver alloy Silver (Ag) 7440-22-4 0.01 2.0 0.11 Lead alloy Lead (Pb) 7439-92-1 0.2 80.0 4.9 Wire Pure metal Aluminium (Al) 7429-90-5 0.2 100.0 4.08 Lead Frame Inon-nickel alloy Phosphorous (P) 7723-14-0 0.2 100 4.08 Lead Frame Inon-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 1.35 Post-plating Pure metal Tin (Sn) 7440-50-9 6.7 9.99 1.374-62 Post-plating Pure metal Tin (Sn) 7440-51-5 1.01 10.0 2.08 Mould Polymer Phenol Formaldehyde resin (gene	External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire Tin alloy Tin (Sn) 7440-31-5 0.03 10.0 0.56 Solder Wire Silver alloy Silver (Ag) 7440-22-4 0.01 2.0 0.11 Lead alloy Lead (Pb) 7439-92-1 0.24 88.0 4.91 Wire Pure metal Aluminium (Al) 7429-90-5 0.2 100.0 4.08 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Post-plating Pure metal Tin (Sn) 7440-02-0 0.73 1.08 1359.35 Post-plating Pure metal Tin (Sn) 7440-02-0 0.73 1.08 1374.62 Post-plating Pure metal Tin (Sn) 7440-31-5 1.01 100.0 20.68 Moould Compound Polymer Phenol Formaldehyde resin (generic) 25928-94-3 3.05 1.00 62.1 Filler	Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.01	1.0	0.1
Solder Wire Tin alloy Tin (Sn) 7440-31-5 0.03 10.0 0.56 Image: Solder Alloy Silver (Ag) 7440-22-4 0.01 2.0 0.11 Lead alloy Lead (Pb) 7439-92-1 0.24 88.0 4.91 Wire Pure metal Aluminium (Al) 7429-90-5 0.2 100.0 4.08 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-50-8 66.72 98.79 1359-35 Post-plating Pure metal Tin (Sn) 7440-50-8 66.72 98.79 1374-62 Post-plating Pure metal Tin (Sn) 7440-50-8 66.72 98.79 1374-62 Post-plating Pure metal Tin (Sn) 7440-50-8 1.01 100.0 20.68 Mould Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Filler Silica fused		Doped silicon	Silicon (Si)	7440-21-3	0.5	99.0	10.1
Silver alloy Silver (Ag) 7440-22-4 0.01 2.0 0.11				Subtotal	0.51	100	10.2
Lead alloy Lead (Pb) 7439-92-1 0.24 88.0 4.91	Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03	10.0	0.56
Wire Pure metal Aluminium (Al) 7429-90-5 0.2 100.0 4.08 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (NI)- cas no. 7440-02-0 7440-02-0 0.73 1.08 1.4.86 Post-plating Pure metal Tin (Sn) 7440-50-8 66.72 98.79 1374.62 Post-plating Pure metal Tin (Sn) 7440-31-5 1.01 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Metal Compound Filler Silica fused 60676-86-0 22.86 75.0 465.75 Mould hydroxide Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Lead Frame Carbon Black Carbon black Carbon black 1333-86-4 0.15 0.5 3.1		Silver alloy	Silver (Ag)	7440-22-4	0.01	2.0	0.11
Wire Pure metal Aluminium (Al) 7429-90-5 0.2 100.0 4.08 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Iron-nickel alloy Opper (Cu) 7440-50-8 66.72 98.79 1359.35 Post-plating Pure metal Tin (Sn) 7440-31-5 1.01 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Mould Compound Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.05 10.0 62.1 Mould Pydroxide Metal hydroxide 60676-86-0 22.86 75.0 465.75 Lead Frame Metal hydroxide 1333-86-4 0.15 0.5 3.1 Lead Frame Subtotal 30.48 100 621		Lead alloy	Lead (Pb)	7439-92-1	0.24	88.0	4.91
Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41				Subtotal	0.28	100	5.58
Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Iron-nickel alloy Copper (Cu) 7440-50-8 66.72 98.79 1359.35 Post-plating Pure metal Tin (Sn) 7440-31-5 1.01 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Filler Silica fused 60676-86-0 22.86 75.0 465.75 Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Carbon Black Carbon black Carbon black 1333-86-4 0.15 0.5 3.1	Wire	Pure metal	Aluminium (AI)	7429-90-5	0.2	100.0	4.08
				Subtotal	0.2	100	4.08
Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Iron-nickel alloy Copper (Cu) 7440-50-8 66.72 98.79 1359.35 Post-plating Pure metal Tin (Sn) 7440-31-5 1.01 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy 25928-94-3 3.05 10.0 62.1 Filler Silica fused 60676-86-0 22.86 75.0 465.75 Metal hydroxide Metal hydroxide 3.05 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 621	Lead Frame		Phosphorous (P)	7723-14-0	0.02	0.03	0.41
Note Post-plating Pure metal Tin (Sn) 7440-30-8 66.72 98.79 1359.35			Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.73	1.08	14.86
Post-plating Pure metal Tin (Sn) 7440-31-5 1.01 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.05 10.0 62.1 Metal hydroxide Metal hydroxide 60676-86-0 22.86 75.0 465.75 Metal hydroxide 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 621			Copper (Cu)	7440-50-8	66.72	98.79	1359.35
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.05 10.0 62.1 Metal hydroxide Metal hydroxide 60676-86-0 22.86 75.0 465.75 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 621				Subtotal	67.47	99.9	1374.62
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.05 10.0 62.1 Filler Silica fused 60676-86-0 22.86 75.0 465.75 Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Carbon Black Carbon black Subtotal 30.48 100 621	Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.01	100.0	20.68
Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.37 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.05 10.0 62.1 Filler Silica fused 60676-86-0 22.86 75.0 465.75 Metal hydroxide Metal hydroxide 3.05 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 621				Subtotal	1.01	100	20.68
Filler Silica fused 60676-86-0 22.86 75.0 465.75 Metal hydroxide Metal hydroxide 3.05 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 62.1		Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.37	4.5	27.95
Metal hydroxide 3.05 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 621		Polymer		25928-94-3	3.05	10.0	62.1
hydroxide Metal hydroxide 3.05 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.48 100 621		Filler	Silica fused	60676-86-0	22.86	75.0	465.75
Subtotal 30.48 100 621			Metal hydroxide		3.05	10.0	62.1
		Carbon Black	Carbon black	1333-86-4	0.15	0.5	3.1
Total 99.95 100 2036.16				Subtotal	30.48	100	621
				Total	99.95	100	2036.16

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